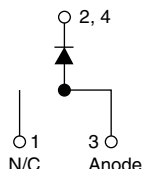


# Hyperfast Rectifier, 4 A FRED Pt®



DPAK (TO-252AA)



## FEATURES

- Hyperfast recovery time
- 175 °C max. operating junction temperature
- Output rectification freewheeling
- Low forward voltage drop reduced  $Q_{rr}$  and soft recovery
- Low leakage current
- AEC-Q101 qualified
- Meets JESD 201 class 2 whisker test
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## PRIMARY CHARACTERISTICS

$I_{F(AV)}$	4 A
$V_R$	200 V
$V_F$ at $I_F$	0.71 V
$t_{rr}$ (typ.)	23 ns
$T_J$ max.	175 °C
Package	DPAK (TO-252AA)
Circuit configuration	Single

## DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers specifically designed with optimized performance of forward voltage drop and hyperfast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	$V_{RRM}$		200	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 164\text{ °C}$	4	A
Non-repetitive peak surge current	$I_{FSM}$	$T_J = 25\text{ °C}$	80	
Peak repetitive forward current	$I_{FM}$	$T_C = 164\text{ °C}$ , $f = 20\text{ kHz}$ , $d = 50\%$	8	
Operating junction and storage temperatures	$T_J$ , $T_{Stg}$		-65 to +175	°C

## ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ °C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}$ , $V_R$	$I_R = 100\text{ }\mu\text{A}$	200	-	-	V
Forward voltage	$V_F$	$I_F = 4\text{ A}$	-	0.87	0.95	
		$I_F = 4\text{ A}$ , $T_J = 150\text{ °C}$	-	0.71	0.80	
Reverse leakage current	$I_R$	$V_R = V_R$ rated	-	-	3	$\mu\text{A}$
		$T_J = 150\text{ °C}$ , $V_R = V_R$ rated	-	2	20	
Junction capacitance	$C_T$	$V_R = 200\text{ V}$	-	17	-	pF
Series inductance	$L_S$	Measured lead to lead 5 mm from package body	-	8	-	nH

<b>DYNAMIC RECOVERY CHARACTERISTICS</b> ( $T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1.0\text{ A}$ , $di_F/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	23	-	ns
		$I_F = 1.0\text{ A}$ , $di_F/dt = 50\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	24	-	
		$T_J = 25\text{ }^{\circ}\text{C}$	-	20	-	
		$T_J = 125\text{ }^{\circ}\text{C}$	-	27	-	
Peak recovery current	$I_{RRM}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	2	-	A
		$T_J = 125\text{ }^{\circ}\text{C}$	-	3.4	-	
Reverse recovery charge	$Q_{rr}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	20	-	nC
		$T_J = 125\text{ }^{\circ}\text{C}$	-	46	-	

<b>THERMAL - MECHANICAL SPECIFICATIONS</b>						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	$T_J$ , $T_{Stg}$		-65	-	175	$^{\circ}\text{C}$
Thermal resistance, junction to case per leg	$R_{thJC}$		-	2.7	3.2	$^{\circ}\text{C}/\text{W}$
Approximate weight				0.3		g
				0.01		oz.
Marking device		Case style DPAK (TO-252AA)		4EWH02FNH		

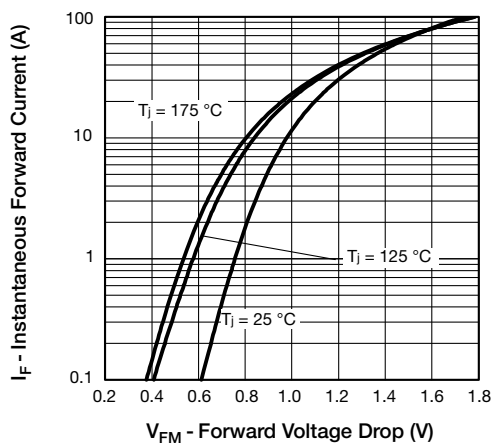


Fig. 1 - Typical Forward Voltage Drop Characteristics

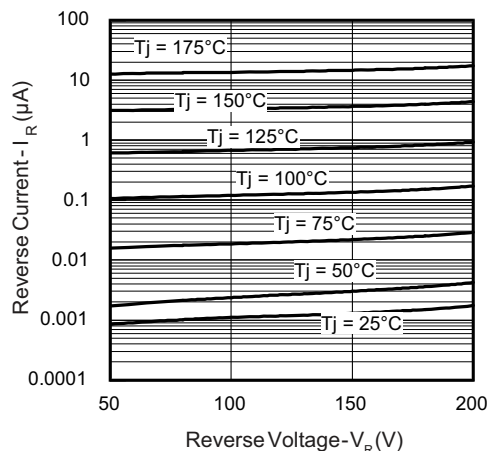


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

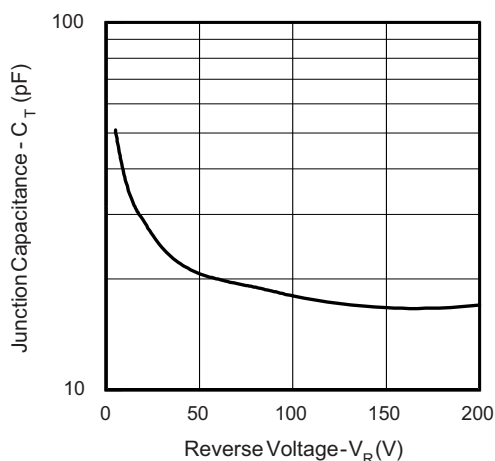


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

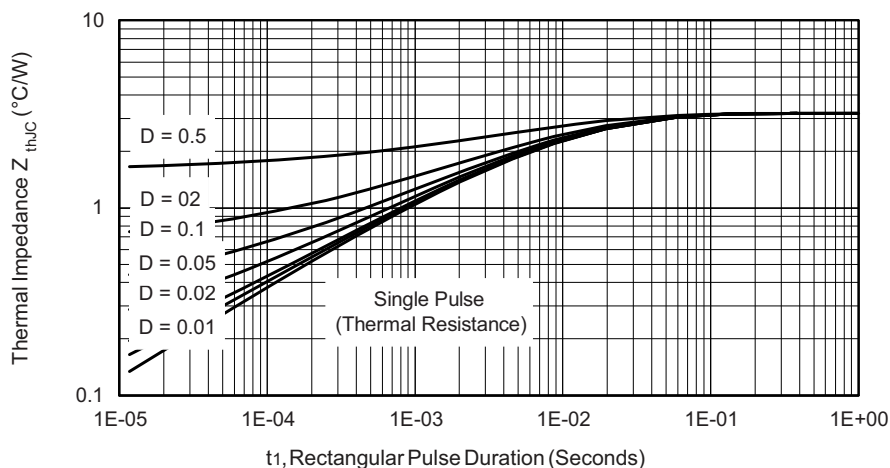
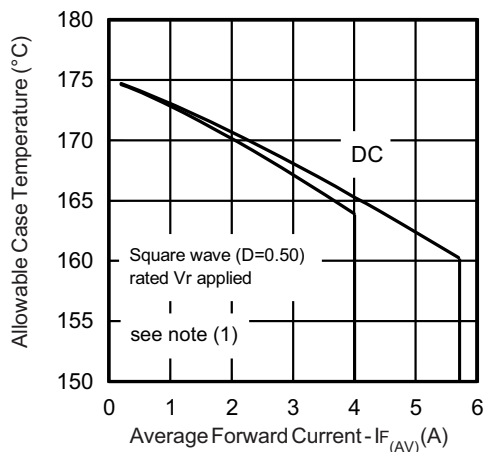

Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

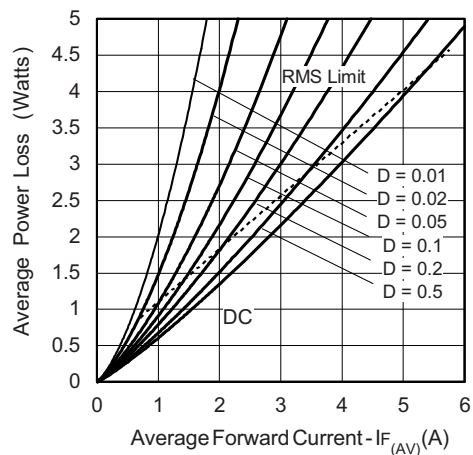
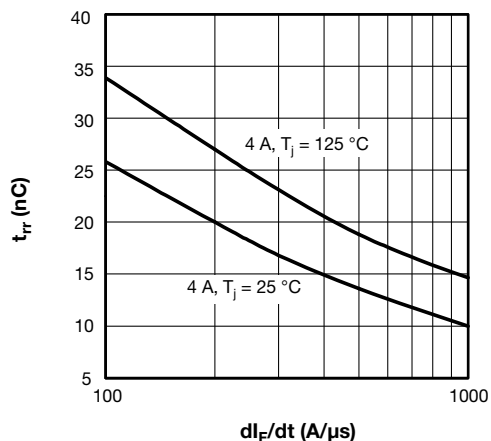
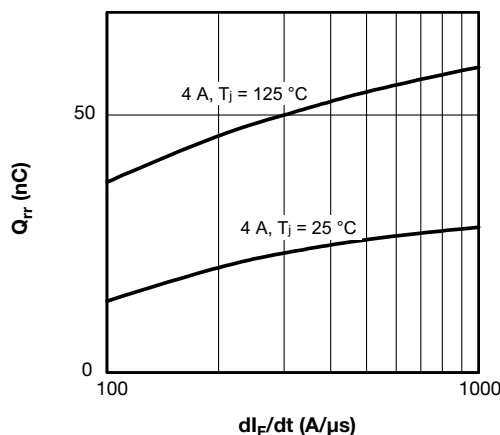


Fig. 6 - Forward Power Loss Characteristics


Fig. 7 - Typical Reverse Recovery Time vs.  $di_F/dt$ 

Fig. 8 - Typical Stored Charge vs.  $di_F/dt$ 

#### Note

- (1) Formula used:  $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$ ;  
 $P_d$  = forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);  
 $P_{dREV}$  = inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1}$  = rated  $V_R$

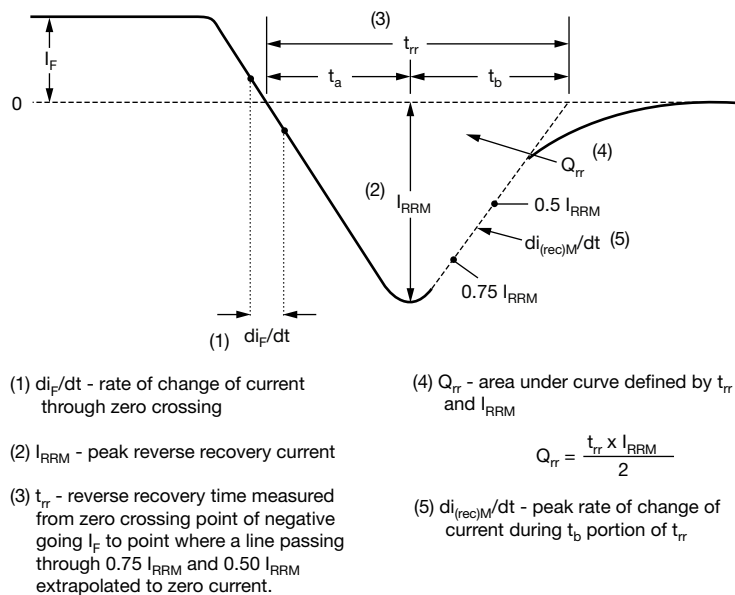


Fig. 9 - Reverse Recovery Waveform and Definitions

**ORDERING INFORMATION TABLE**

Device code	VS-	4	E	W	H	02	FN	TRL	H	M3
	1	2	3	4	5	6	7	8	9	10
1	-	Vishay Semiconductors product								
2	-	Current rating (4 = 4 A)								
3	-	Circuit configuration:								
		E = single diode								
4	-	Package identifier:								
		W = DPAK								
5	-	H = hyperfast recovery								
6	-	Voltage rating (02 = 200 V)								
7	-	FN = TO-252AA								
8	-	<ul style="list-style-type: none"><li>• None = tube</li><li>• TR = tape and reel</li><li>• TRL = tape and reel (left oriented)</li><li>• TRR = tape and reel (right oriented)</li></ul>								
9	-	H = AEC-Q101 qualified								
10	-	Environmental digit:								
		M3 = halogen-free, RoHS compliant, and terminations lead (Pb)-free								

ORDERING INFORMATION (Example)		
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-4EWH02FNHM3	75	Antistatic plastic tube
VS-4EWH02FNTRHM3	2000	13" diameter reel
VS-4EWH02FNTRLHM3	3000	13" diameter reel
VS-4EWH02FNTRRHM3	3000	13" diameter reel

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95519">www.vishay.com/doc?95519</a>
Part marking information	<a href="http://www.vishay.com/doc?95518">www.vishay.com/doc?95518</a>
Packaging information	<a href="http://www.vishay.com/doc?95033">www.vishay.com/doc?95033</a>
SPICE model	<a href="http://www.vishay.com/doc?95381">www.vishay.com/doc?95381</a>

### DPAK (TO-252AA)

#### DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	0.086	0.094	
A1	-	0.13	-	0.005	
b	0.64	0.89	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	3
c	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	5
D1	4.93	-	0.194	-	3
E	6.35	6.73	0.250	0.265	5
E1	4.32	-	0.170	-	3

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
e	2.29 BSC		0.090 BSC		
H	9.40	10.41	0.370	0.410	
L	1.40	1.78	0.055	0.070	
L1	2.74 BSC		0.108 REF.		
L2	0.51 BSC		0.020 BSC		
L3	0.89	1.27	0.035	0.050	3
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	2

#### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Dimensions D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (5) Outline conforms to JEDEC® outline TO-252AA, except for D1 dimension



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